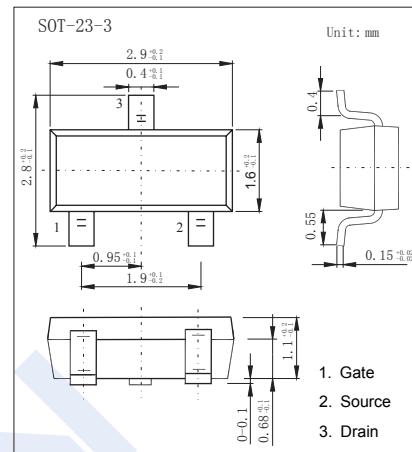
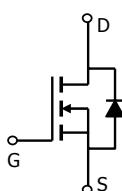


N-Channel Enhancement MOSFET

SI2324DS (KI2324DS)

■ Features

- $V_{DSS} = 100V$
- $I_D = 2.3 A$ ($V_{GS} = 10V$)
- $R_{DS(ON)} < 234m\Omega$ ($V_{GS} = 10V$)
- $R_{DS(ON)} < 267m\Omega$ ($V_{GS} = 6V$)
- $R_{DS(ON)} < 278m\Omega$ ($V_{GS} = 4.5V$)

■ Absolute Maximum Ratings $T_a = 25^\circ C$

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current $T_J = 150^\circ C$ *1	I_D TA=25°C	2.3	A
	I_D TA=70°C	1.8	
Pulsed Drain Current	I_{DM}	5	
Power Dissipation	P_D TA=25°C	2.5	W
	P_D TA=70°C	1.6	
Thermal Resistance.Junction- to-Ambient	R_{thJA}	100	$^\circ C/W$
Thermal Resistance.Junction- to-Case	R_{thJC}	50	
Junction Temperature	T_J	150	$^\circ C$
Storage Temperature Range	T_{stg}	-55 to 150	

*1 Surface Mounted on 1" x 1" FR4 Board.

N-Channel Enhancement MOSFET

SI2324DS (KI2324DS)

■ Electrical Characteristics $T_a = 25^\circ\text{C}$

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V_{DSS}	$I_D=250 \mu\text{A}, V_{GS}=0\text{V}$	100			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=100\text{V}, V_{GS}=0\text{V}$			1	μA
		$V_{DS}=100\text{V}, V_{GS}=0\text{V}, T_J=55^\circ\text{C}$			10	
Gate-Body Leakage Current	I_{GSS}	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$			± 100	nA
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS}=V_{GS}, I_D=250 \mu\text{A}$	1.2		2.8	V
Static Drain-Source On-Resistance ^a	$R_{DS(\text{ON})}$	$V_{GS}=10\text{V}, I_D=1.5\text{A}$		195	234	$\text{m}\Omega$
		$V_{GS}=6\text{V}, I_D=1\text{A}$		222	267	
		$V_{GS}=4.5\text{V}, I_D=0.5\text{A}$		231	278	
On State Drain Current ^a	$I_{D(\text{ON})}$	$V_{GS}=4.5\text{V}, V_{DS} \geq 5\text{V}$	5			A
Forward Transconductance ^a	g_{FS}	$V_{DS}=20\text{V}, I_D=1.5\text{A}$		2		S
Input Capacitance	C_{iss}	$V_{GS}=0\text{V}, V_{DS}=50\text{V}, f=1\text{MHz}$		190		pF
Output Capacitance	C_{oss}			22		
Reverse Transfer Capacitance	C_{rss}			13		
Gate Resistance	R_g	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$	0.3	1.4	2.8	Ω
Total Gate Charge	Q_g	$V_{GS}=4.5\text{V}, V_{DS}=50\text{V}, I_D=1.6\text{A}$		5.2	10.4	nC
Gate Source Charge	Q_{gs}			0.75		
Gate Drain Charge	Q_{gd}			1.4		
Turn-On DelayTime	$t_{d(on)}$	$V_{GS}=4.5\text{V}, V_{DS}=50\text{V}, R_L=39\Omega, R_{GEN}=1\Omega$		30	45	ns
Turn-On Rise Time	t_r			26	39	
Turn-Off DelayTime	$t_{d(off)}$			17	26	
Turn-Off Fall Time	t_f			12	20	
Body Diode Reverse Recovery Time	t_{rr}	$I_F=1.3\text{A}, dI/dt=100\text{A}/\mu\text{s}$		22	33	
Body Diode Reverse Recovery Charge	Q_{rr}	$I_F=1.3\text{A}, dI/dt=100\text{A}/\mu\text{s}$		21	32	nC
Maximum Body-Diode Continuous Current	I_S				2.1	A
Diode Forward Voltage	V_{SD}	$I_S=1.3\text{A}, V_{GS}=0\text{V}$		0.8	1.2	V

a.Pulse test ; pulse width $\leq 300 \mu\text{s}$,duty cycle $\leq 2\%$

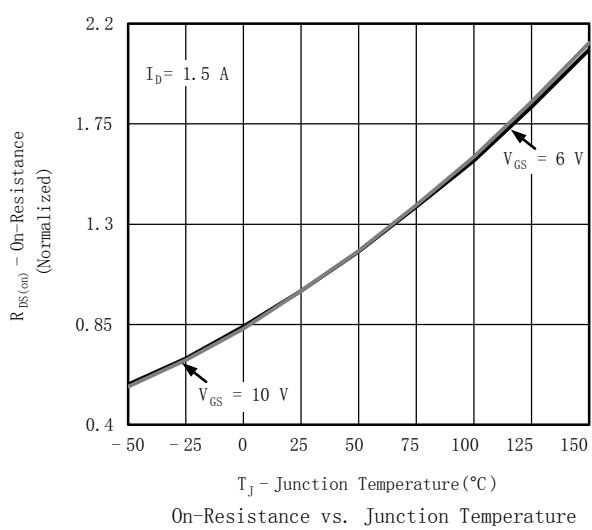
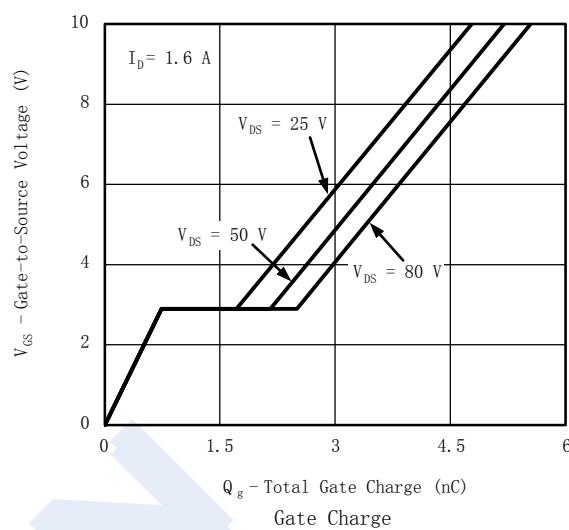
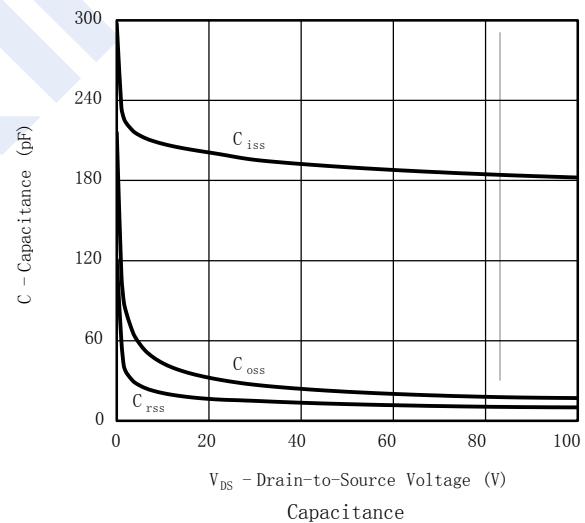
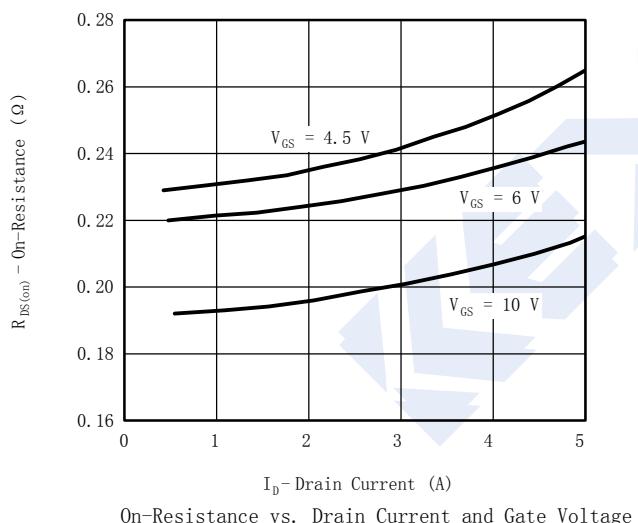
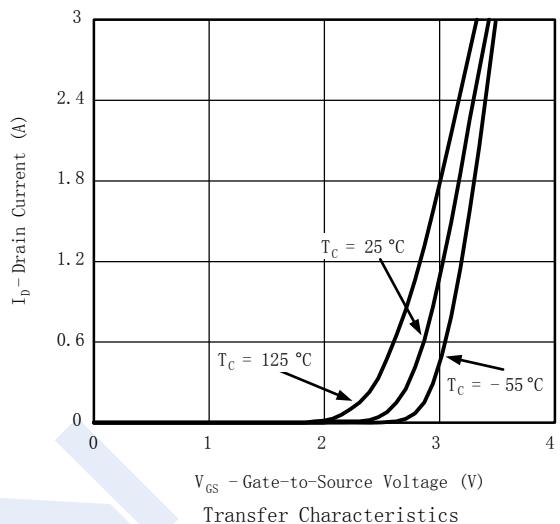
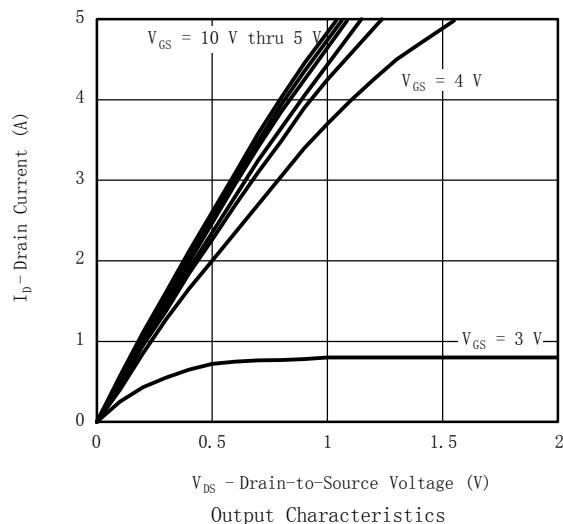
■ Marking

Marking	D 4*
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N-Channel Enhancement MOSFET

SI2324DS (KI2324DS)

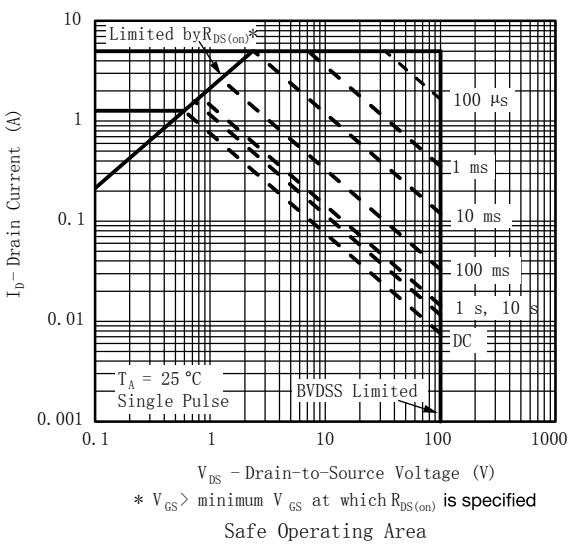
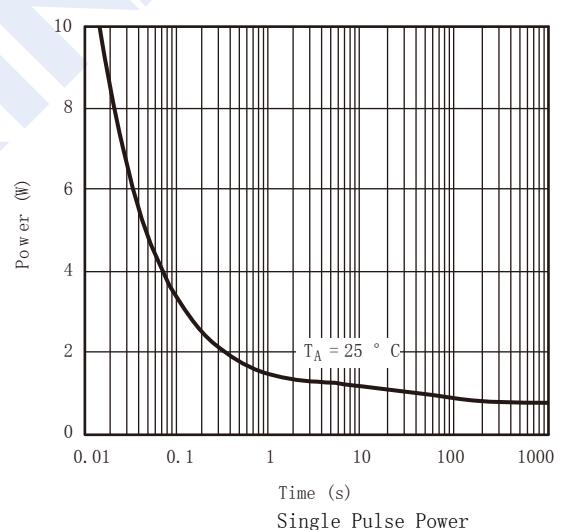
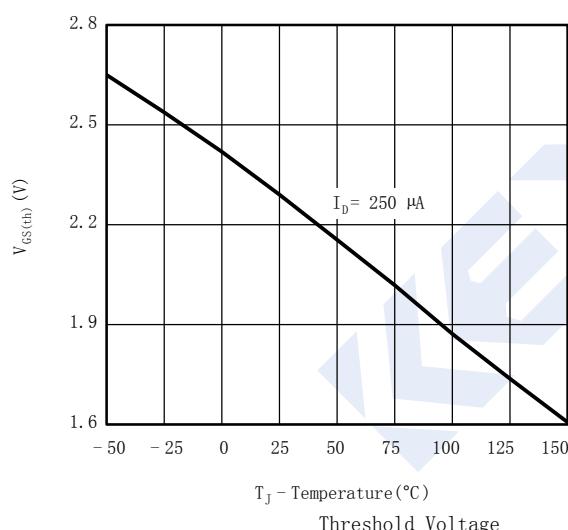
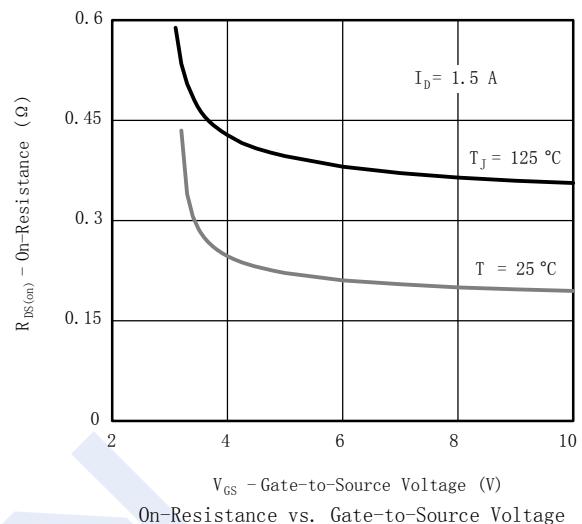
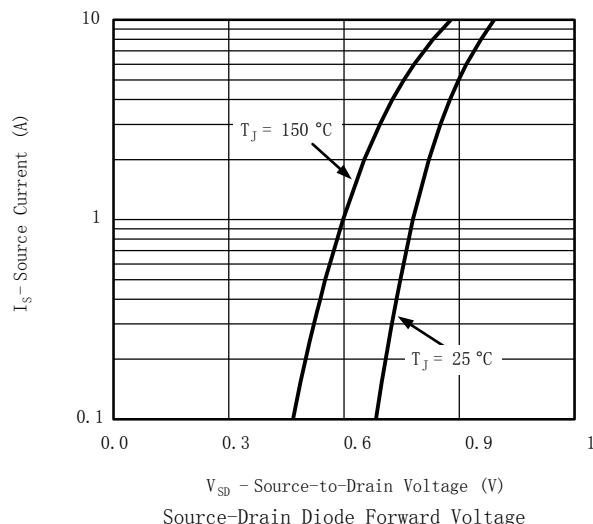
■ Typical Characteristics



N-Channel Enhancement MOSFET

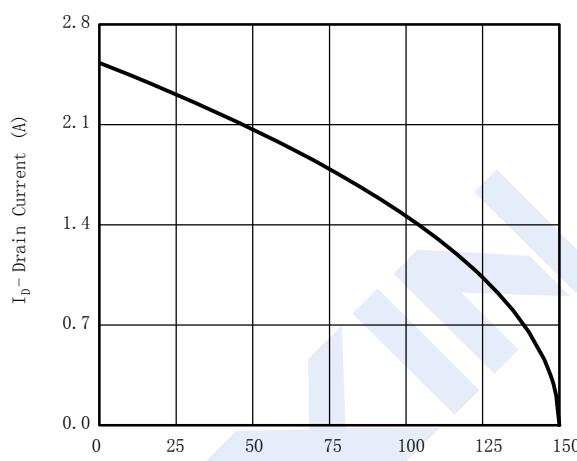
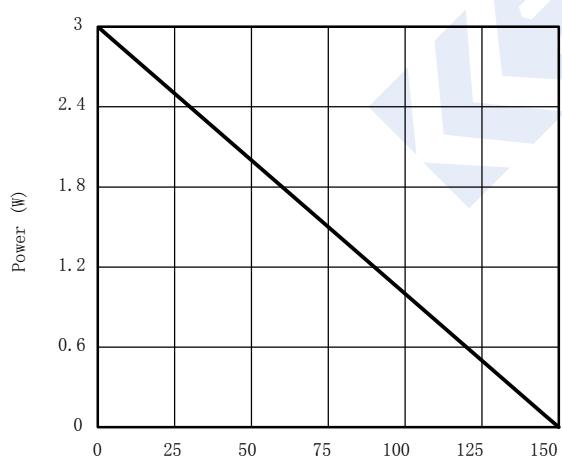
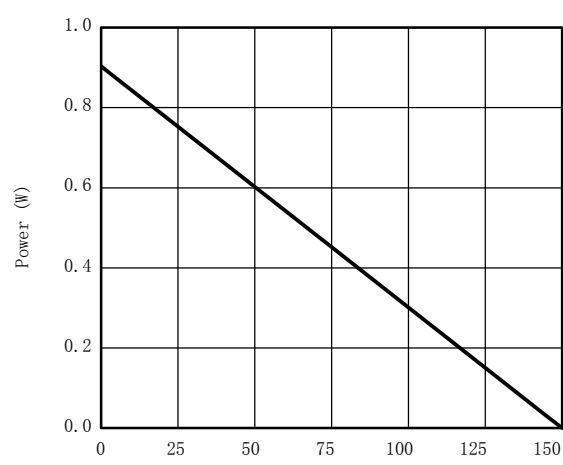
SI2324DS (KI2324DS)

■ Typical Characteristics



N-Channel Enhancement MOSFET**SI2324DS (KI2324DS)**

■ Typical Characteristics

 T_C - Case Temperature (°C)
Current Derating* T_C - Case Temperature (°C)
Power, Junction-to-Foot T_A - Ambient Temperature (°C)
Power, Junction-to-Ambient

N-Channel Enhancement MOSFET**SI2324DS (KI2324DS)****■ Typical Characteristics**